LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1076HVIT#PBF **(Engineering Calculation)** TO-220

TOTAL MASS (g): **1.99241**

(printed on: 4/18/2011 2:20:06 AM)

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.005956**	**1000000**	**2989.344**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	1.428754	998500	717098.3
		Iron (Fe)	7439-89-6	0	0	0
		Phosporus (P)	7723-14-0	0	0	0
		Zinc (Zn)	7440-66-6	0	0	0
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0.002146	1500	1077.087
		Lead Frame Total:		**1.433046**	**1000000**	**719252.4**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.01139827	1000000	5720.844
		External Plating Total:		**0.01139827**	**1000000**	**5720.844**
		Inter. Plating Ni	7440-02-0	0.01	834028.4	5019.046
		Inter. Plating Ag	7440-22-4	0.00199	165971.6	998.7903
		Internal Plating Total:		**0.01199**	**1000000**	**6017.837**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0	0	0
		Tin (Sn)	7440-31-5	0.000129	50000	64.7457
		Lead (Pb)	7439-92-1	0.002453	950000	1231.172
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0	0	0
		Die Attach Total:		**0.002582**	**1000000**	**1295.918**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.05427	103000	27238.37
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.471567	895000	236681.7
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0	0	0
		Carbon Black (C)	1333-86-4	0.001054	2000	529.0075
		Encapsulation Total:		**0.526891**	**1000000**	**264449**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**0.000547**	**1000000**	**274.5418**